

Wi-Fi® MCU Modules

ElectricImp modules

electric imp

 **Type 1GC/Imp005**
PN: LBWA1UZ1GC-958
PN: LBWA1UZ1GC-901 (Imp005)
CYW43907 Chipset
10.0 x 10.0 x 1.3 mm



WICED, ElectricImp
FCC/IC/CE* Reference Certified



802.11 a/b/g/n
+ Ethernet + ARM Cortex- R4

 **Type 1MD/Imp004m**
PN: LBEE5ZZ1MD-011
CYW43438+STM Chipset
21.0 x 17.5 x 2.3 mm

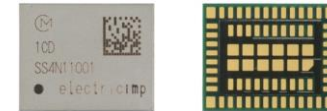


ElectricImp
FCC/IC/CE*/Japan Certified



802.11 b/g/n + Bluetooth® 4.1
+ ARM Cortex- M4

 **Type 1CD/Imp003**
PN:LBWA1ZV1CD-716
CYW43362+STM Chipset
10.0 x 7.9 x 1.25 mm



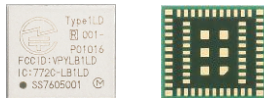
ElectricImp
FCC/IC/CE* Reference Certified



802.11 b/g/n
+ ARM Cortex-M4

Ayla modules

 **Type 1LD**
PN: LBEE5PA1LD-005
PN: LBEE5PA1LD-222(Ayla)
CYW43438+STM Chipset
8.9 x 7.8 x 1.2 mm



WICED, Ayla
FCC/IC/CE*/Japan Certified



802.11 b/g/n + Bluetooth® 4.2
+ ARM Cortex-M4

 **Type 1AD**
PN: LBWA1CS1AD-806
CYW4390 Chipset
9.4 x 8.9 x 1.2 mm



Ayla
FCC/IC/CE* Reference Certified



802.11 b/g/n + ARM Cortex-M3

 **Ayla Networks**



Built-in Cloud Agent *Conducted results for CE Marking Conformity Assessment Procedures are available

Wi-Fi MCU modules

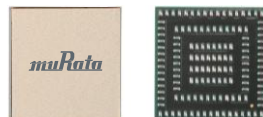


Type 1PS

PN: LBWA1UZ1PS-241

CYW54907 Chipset

10.0 x 10.0 x 1.3 mm



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802.11 a/b/g/n/ac + Bluetooth®



Wi-Fi/BT MCU modules

Type 1QP

PN: LBEE5WQ1QP-276

CYW43907+CYW20707 Chipset

11.0 x 11.0 x 1.2 mm



WICED



802.11 a/b/g/n + Bluetooth® 5.0
+ ARM Cortex- R4

Type 1QX

PN: LBEE5WQ1QX-277

CYW54907+CYW20707 Chipset

11.0 x 11.0 x 1.2 mm



WICED



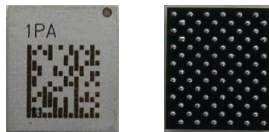
802.11 a/b/g/n + Bluetooth® 5.0
+ ARM Cortex- R4

Bluetooth®/ BLE Modules



Type 1PA

PN: LBCA1KU1PA-245
CYW20719 Chipset
5.9 x 5.1 x 1.17mm

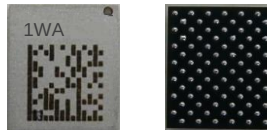


Bluetooth/BLE
WICED Studio

Bluetooth® 5.0

Type 1WA

PN: LBCA1KU1WA
CYW20721 Chipset
5.9 x 5.1 x 1.17mm



Bluetooth/BLE
WICED Studio

Bluetooth® 5.0

Type 1GR

PN: LBCA1ZZ1GR-084
CYW20736 chipset
9.0 x 7.0 x 1.2mm



BLE
WICED Studio
FCC/IC/CE*/Japan Certified

Bluetooth® 4.1



*Conducted results for CE Marking Conformity Assessment Procedures are available

Wi-Fi®/ Bluetooth® Modules

Wi-Fi® + Bluetooth® MCU modules

Type 1KP/1KQ/1KR/1KS

PN: LBWA1ZZ1KP-289

PN: LBWA1ZZ1KQ-290

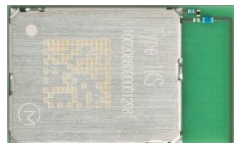
PN: LBWA1ZZ1KR-291

PN: LBWA1ZZ1KS-088

TI CC3120/CC3220

CC3220S/CC3220SF

13.2 x 21.45 x 2.65mm



SimpleLink Gen2 SDK

802.11 b/g/n

+ ARM Cortex- M3

FCC/IC/CE*/Japan Certified

Wi-Fi® + Bluetooth® modules

Type WT

PN: LBEP5CLWTC-631

WL1801/1831 Chipset

9.9 x 8.8 x1.3 mm

-40 ~ 75°C



802.11 b/g/n + Bluetooth® 4.2

Type WM

PN: LBEP5CLWMC-633

WL1803/1833 Chipset

9.9 x 8.8 x1.3 mm

-40 ~ 75°C



802.11 a/b/g/n + Bluetooth® 4.2

Japan Certified

Type XR

PN: LBEP5CLXRC-701

WL1801 Chipset

9.9 x 8.8 x1.3 mm

-40 ~ 85°C



802.11 b/g/n